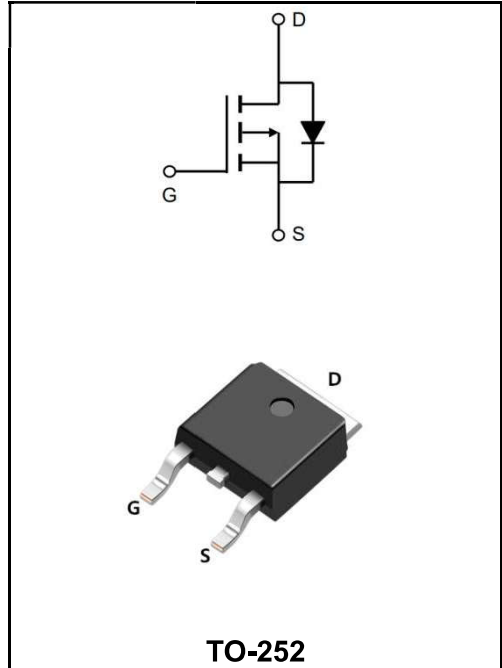


-100V P-CHANNEL ENHANCEMENT MODE MOSFET

MAIN CHARACTERISTICS

I_D	-15A
V_{DSS}	-100V
R_{DS(on)-typ(@V_{GS}=-10V)}	< 185mΩ(Type:145 mΩ)



Application

- ◆Brushless motor
- ◆Load switch
- ◆Uninterruptible power supply

Product Specification Classification

Part Number	Package	Marking	Pack
YFW15P10AD	TO-252	YFW 15P10AD XXXXX	2500PCS/Tape

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	-100	V
Gate - Source Voltage	V_{GS}	±20	V
Continuous Drain Current, V _{GS} @ -10V ¹ @T _C =25°C	I_D	-15	A
Continuous Drain Current, V _{GS} @ -10V ¹ @T _C =100°C	I_D	-12	A
Pulsed Drain Current ²	I_{DM}	-45	A
Single Pulse Avalanche Energy ³	E_{AS}	56	mJ
Avalanche Current	I_{AS}	-15	A
Total Power Dissipation ⁴ @T _C =25°C	P_D	50	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C
Thermal Resistance Junction-Ambient ¹	R_{θJA}	62.5	°C/W
Thermal Resistance Junction to Case ¹	R_{θJC}	2.5	°C/W

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	BV_{DSS}	-100	-	-	V
Zero Gate Voltage Drain Current	$V_{DS}=-80V, V_{GS}=0V$	I_{DSS}	-	-	-1	μA
Gate to Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	I_{GSS}	-	-	± 100	nA
Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	$V_{GS(th)}$	-1.0	-	-2.5	V
Static Drain-Source On-Resistance ^{note1}	$V_{GS}=-10V, I_D=-2A$	$R_{DS(ON)}$	-	145	185	m Ω
	$V_{GS}=-4.5V, I_D=-1A$		-	170	200	
Input Capacitance	$V_{DS}=-50V$ $V_{GS}=0V$ $f=1MHz$	C_{iss}	-	1545	-	μF
Output Capacitance		C_{oss}	-	37	-	
Reverse Transfer Capacitance		C_{rss}	-	25	-	
Total Gate Charge	$V_{DS}=-50V$ $I_D=-2A$ $V_{GS}=-10V$	Q_g	-	27	-	nC
Gate-Source Charge		Q_{gs}	-	5.3	-	
Gate-Drain("Miller") Charge		Q_{gd}	-	3.2	-	
Turn-on delay time	$V_{DS}=-50V$ $I_D=-2A$ $R_L=25\Omega$ $V_{GEN}=-10V$ $R_G=4.5\Omega$	$t_{d(on)}$	-	10	-	ns
Turn-on Rise Time		T_r	-	27	-	
Turn-Off Delay Time		$t_{d(OFF)}$	-	288	-	
Turn-Off Fall Time		t_f	-	88	-	
Maximum Continuous Drain to Source Diode Forward Current		I_S	-	-	-18	A
Drain to Source Diode Forward Voltage ^{note1}	$V_{GS}=0V, I_S=-2A$	V_{SD}	-	-	-1.3	V
Reverse Recovery Time	$I_{SD}=-6A, V_{GS}=0V,$ $dI/dt=100A/\mu s$	t_{rr}	-	40	-	ns
Reverse Recovery Charge		Q_{rr}	-	28	-	nC

Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3、 The EAS data shows Max. rating . The test condition is $V_{DD}=-72V, V_{GS}=-10V, L=0.1mH, I_{AS}=-15A$
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

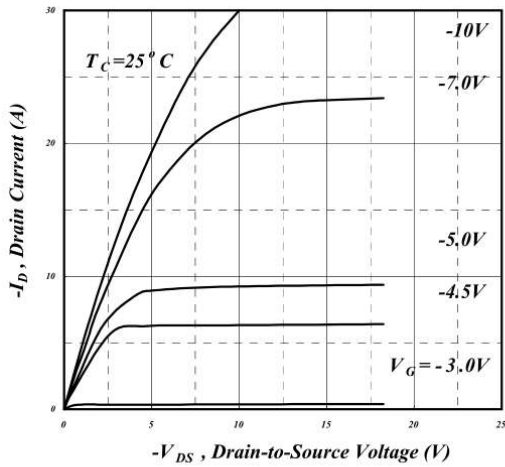


Fig 1. Typical Output Characteristics

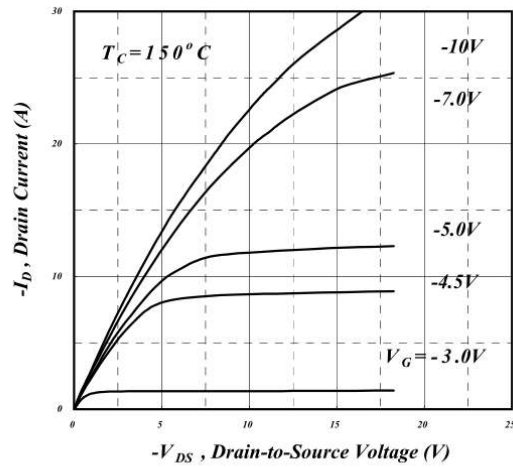


Fig 2. Typical Output Characteristics

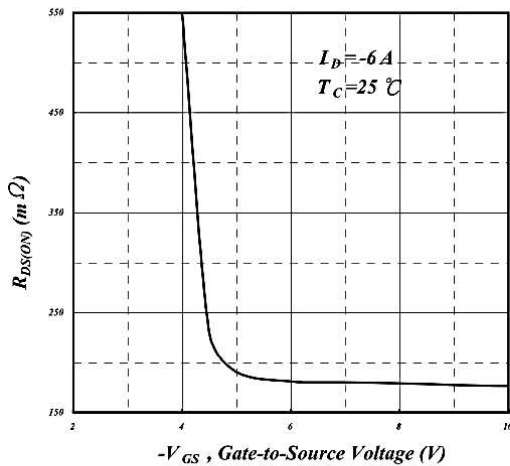


Fig 3. On-Resistance v.s. Gate Voltage

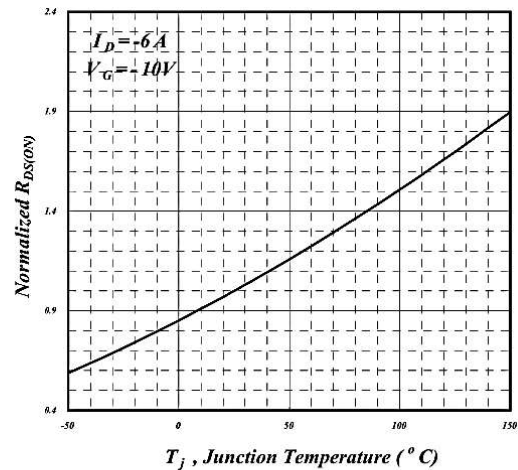


Fig 4. Normalized On-Resistance v.s. Junction Temperature

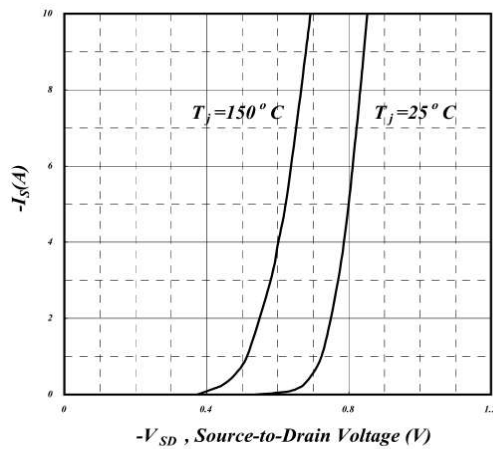


Fig 5. Forward Characteristic of Reverse Diode

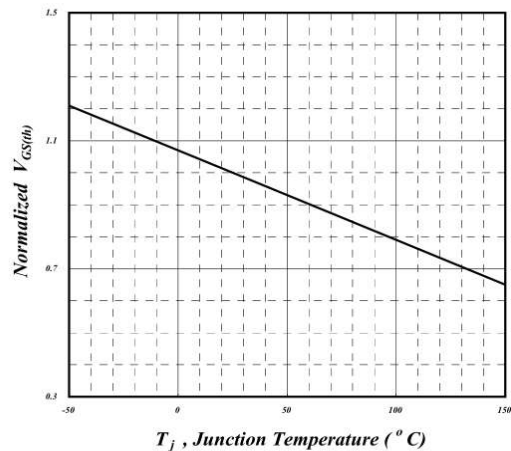


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

Ratings and Characteristic Curves

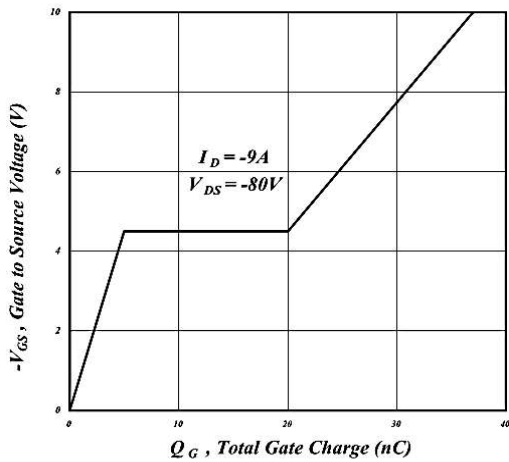


Fig 7. Gate Charge Characteristics

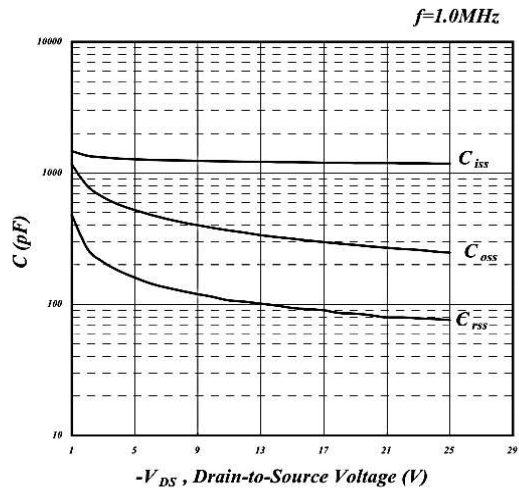


Fig 8. Typical Capacitance Characteristics

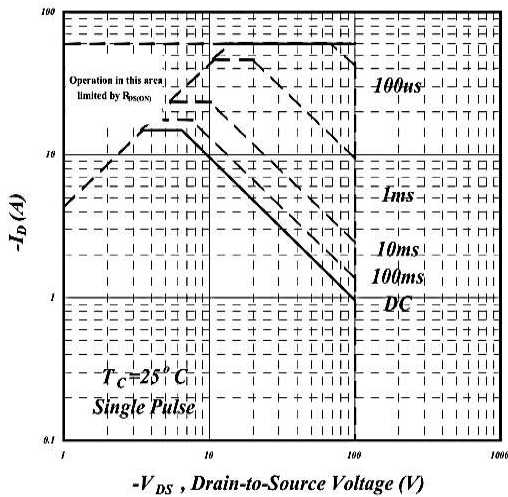


Fig 9. Maximum Safe Operating Area

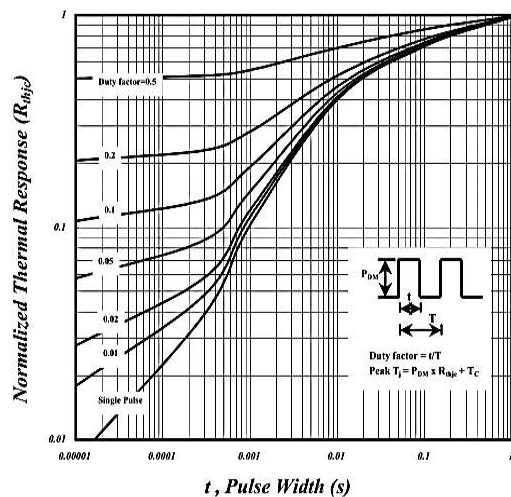


Fig 10. Effective Transient Thermal Impedance

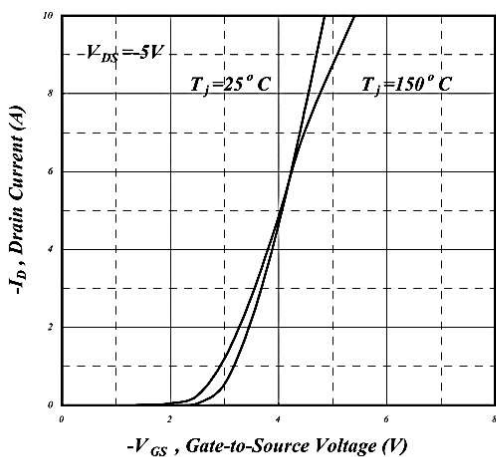


Fig 11. Transfer Characteristics

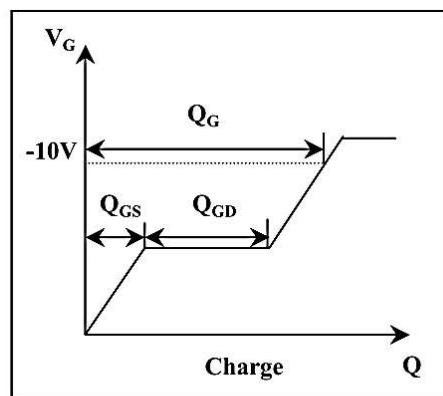


Fig 12. Gate Charge Waveform

Package Outline Dimensions Millimeters

TO-252

Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°
All Dimensions in millimeter			

